TOSHIBA Photointerrupter Infrared LED + Phototransistor

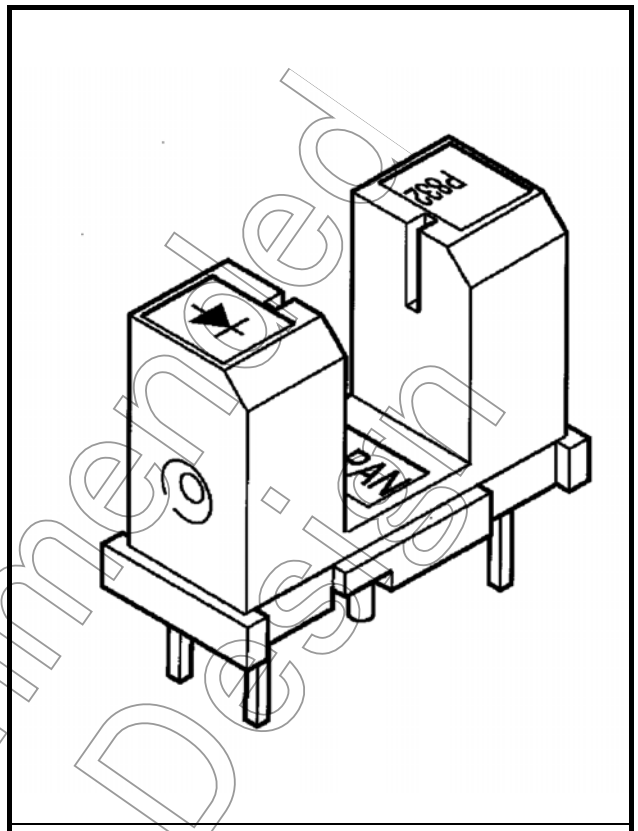
TLP832(F)

Electronic Equipment Such As VCRS And CD Players

Office Equipment Such As Copiers, Printers And Fax Machines

Automatic Vending Machines

Various Position Detection Sensors



TOSHIBA	11−14F1

Weight: 0.58 g (typ.)

The TLP832(F) photointerrupter consists of a GaAs infrared LED and an Si phototransistor. Housed in a short− lead package, this device is ideal for automatic mounting.

- Designed for direct mounting on printed circuit boards (positioning pins included).
- Short leads enabling automatic mounting: Lead length 3.4mm ± 0.3mm
- Board thickness: 1.6mm or less
- Gap: 5mm
- Resolution: Slit width = 0.5mm
- High current transfer ratio: I_C/I_F = 5% (min)
- High temperature operation: T_{opr} = 95°C (max)
- High response speed: t_r, t_f = 15 μs (typ.)
- Detector impermeable to visible light
- package material: Polybutylene terephthalate (UL94V−0, black)

Not Recommended for New Design

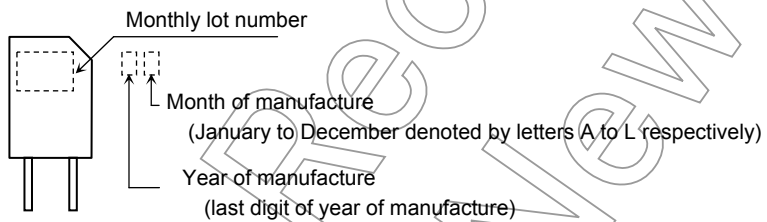
Absolute Maximum Ratings (Ta = 25°C)

Characteristic			Symbol	Rating	Unit
LED	Forward current		I_F	50	mA
	Forward current derating	25°C < Ta ≤ 85°C	ΔI_F / °C	−0.33	mA / °C
		Ta > 85°C		−2	
	Reverse voltage		V_R	5	V
Detector	Collector−emitter voltage		V_{CEO}	35	V
	Emitter−collector voltage		V_{ECO}	5	V
	Collector power dissipation		P_C	75	mW
	Collector power dissipation derating (Ta > 25°C)		ΔP_C / °C	−1	mW / °C
	Collector current		I_C	50	mA
Operating temperature			T_{opr}	−30 to 95	°C
Storage temperature			T_{stg}	−40 to 100	°C
Soldering temperature (5 s)		(Note 1)	T_{sol}	260	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook (“Handling Precautions”/“Derating Concept and Methods”) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: At the location of 1.5mm from the resin package bottom

Markings



Operating Ranges

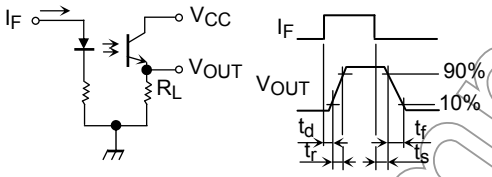
Characteristic	Symbol	Min	Typ.	Max	Unit
Supply voltage	V_{CC}	—	5	24	V
Forward current	I_F	—	—	25	mA
Operating temperature	T_{opr}	−10	—	75	°C

Not Recommended for New Design

Optical And Electrical Characteristics (Ta = 25°C)

	Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
LED	Forward voltage	V_F	I_F = 10mA	1.00	1.15	1.30	V
	Reverse current	I_R	V_R = 5V	—	—	10	μA
	Peak emission wavelength	λ_P	I_F = 10mA	—	940	—	nm
Detector	Dark current	I_D (I_{CEO})	V_{CE} = 24V, I_F = 0	—	—	0.1	μA
	Peak sensitivity wavelength	λ_P		—	870	—	nm
Coupled	Current transfer ratio	I_C / I_F	V_{CE} = 2V, I_F = 10mA	5	—	100	%
	Collector−emitter saturation voltage	$V_{CE\ (sat)}$	I_F = 20mA, I_C = 0.5mA	—	0.1	0.35	V
	Rise time	t_r	V_{CC} = 5V, I_C = 1mA, R_L = 1kΩ (Note 2)	—	15	50	μs
	Fall time	t_f		—	15	50	

(Note 2): Switching time measurement circuit and waveform



Precautions

1. When removing flux with chemicals after soldering, clean only the soldered part of the leads. Do not immerse the entire package in the cleaning solvent. Chemical residue on the LED emitter or the phototransistor may adversely affect the optical characteristics of the device and may drastically reduce the conversion efficiency.
2. Care must taken in relation to the environment in which the device is to be installed.
   Oil or chemicals may cause the package to melt or crack.
3. Mount the device on a level surface.
4. Keep the device away from external light. Although the phototransistor is of low optical sensitivity, the device may malfunction if external light with a wavelength of 700 nm or more is allowed to impinge on it.
5. Conversion efficiency falls over time due to the current which flows in the infrared LED.
   When designing a circuit, take into account this change in conversion efficiency over time.
   The ratio of fluctuation in conversion efficiency to fluctuation in infrared LED optical output is 1:1.

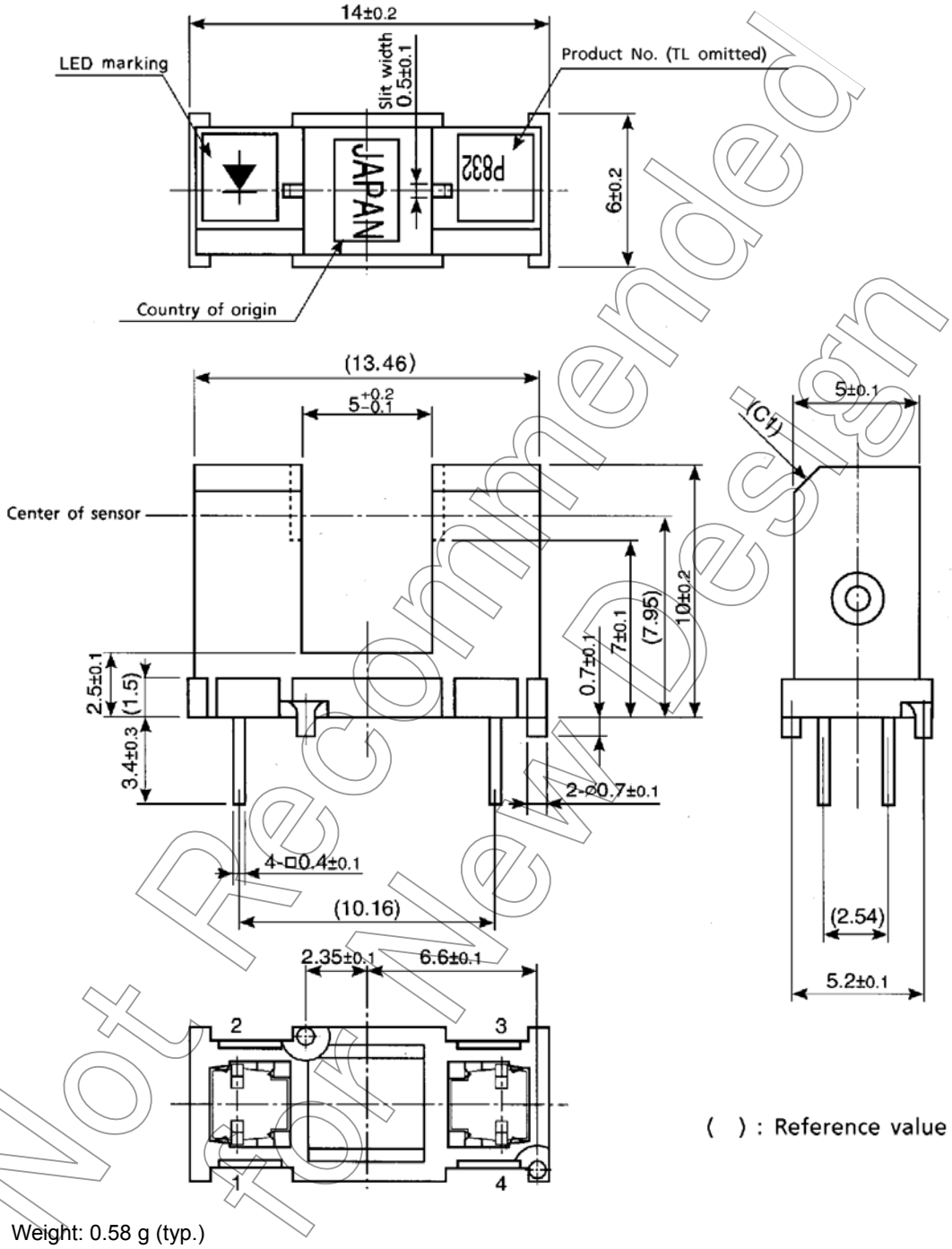
$$\frac{I_C / I_F(t)}{I_C / I_F(0)} = \frac{P_O(t)}{P_O(0)}$$

Not Recommended for New Design

Package Dimensions

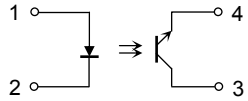
11-14F1

Unit: mm



Weight: 0.58 g (typ.)

Pin Connection



1.Anode
2.Cathode
3.Collector
4.Emitter

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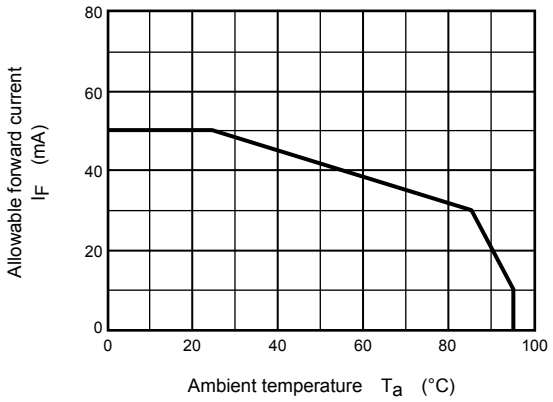
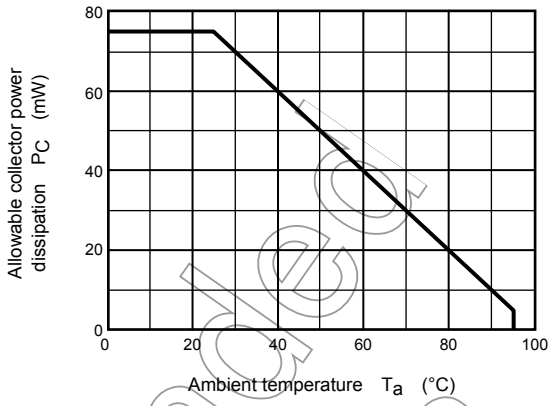
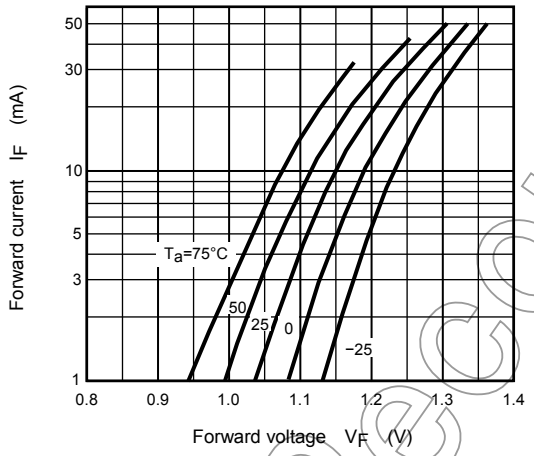
$I_F - T_a$



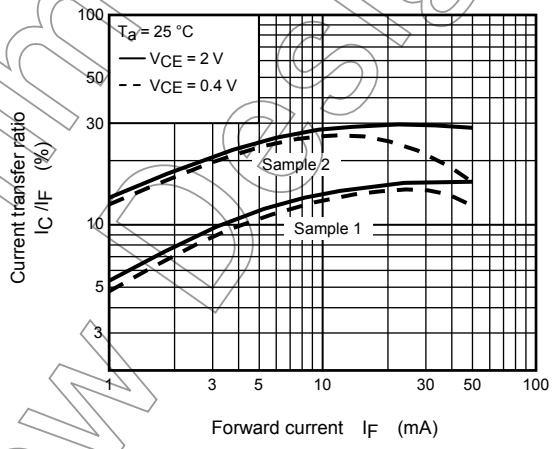
$P_C - T_a$



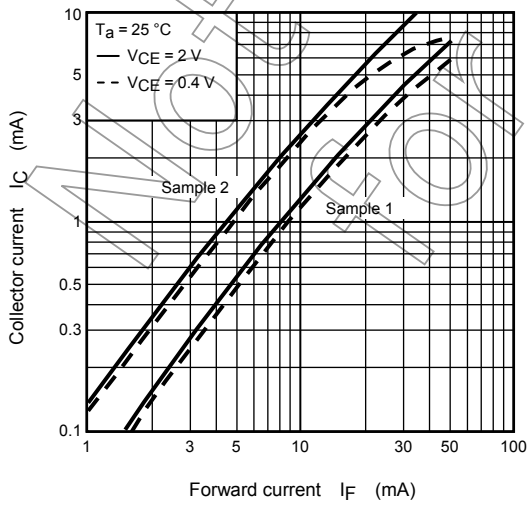
$I_F - V_F$ (typ.)



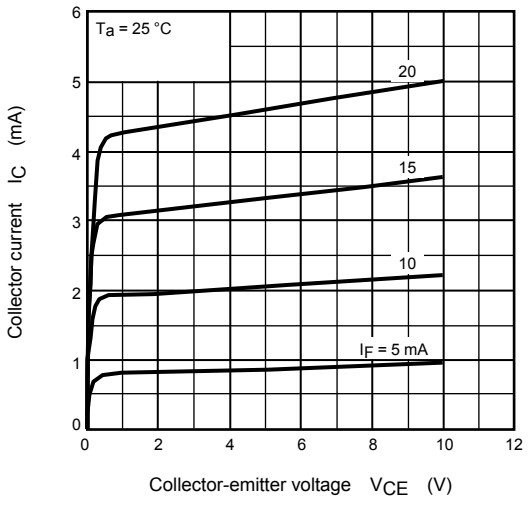
$I_C/I_F - I_F$



$I_C - I_F$



$I_C - V_{CE}$ (typ.)



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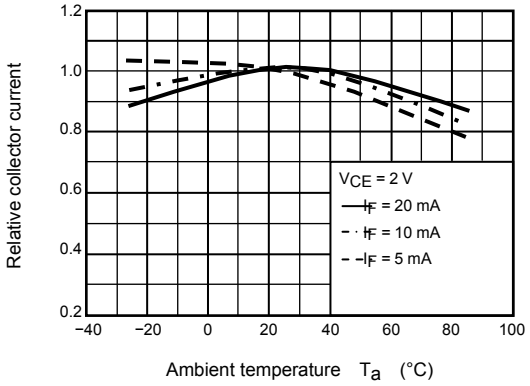
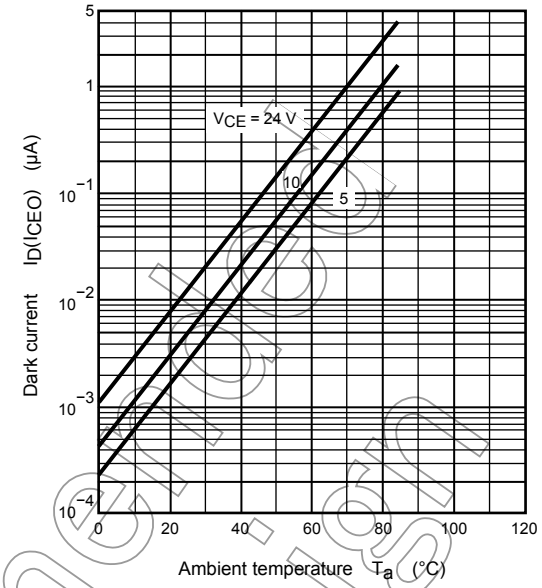
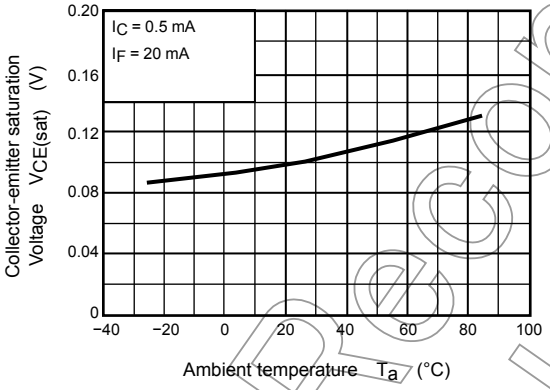
Relative $I_C - T_a$ (typ.)



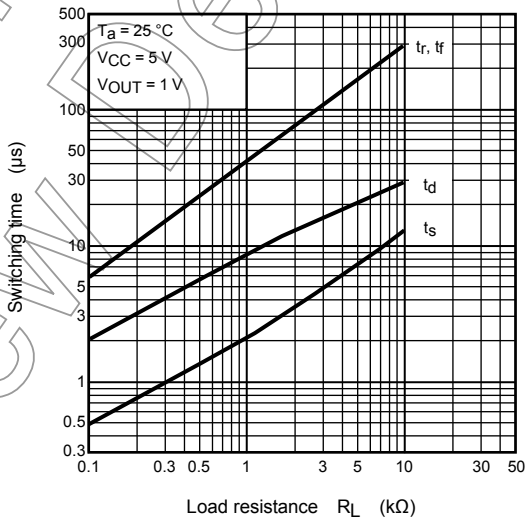
$I_D(I_{CEO}) - T_a$ (typ.)



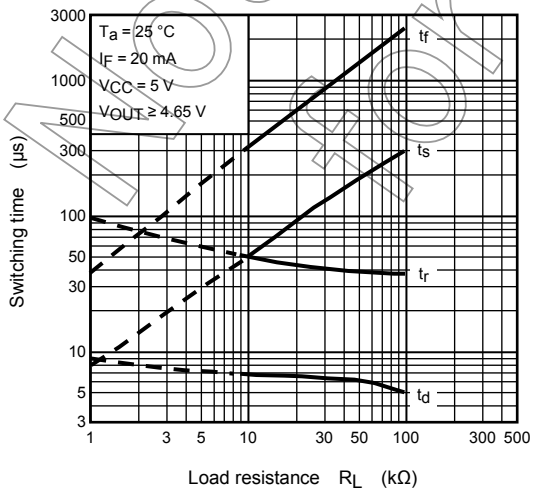
$V_{CE(sat)} - T_a$ (typ.)



Switching characteristics (non saturated operation) (typ.)



Switching characteristics (saturated operation) (typ.)



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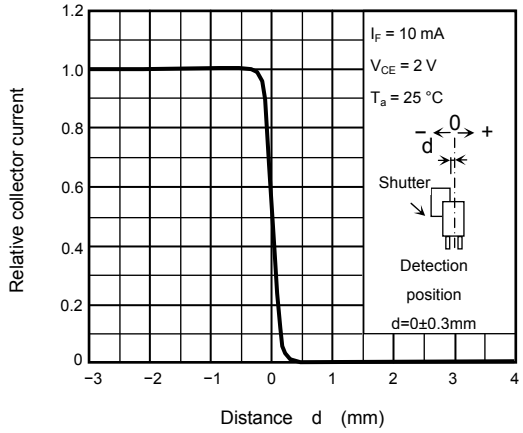
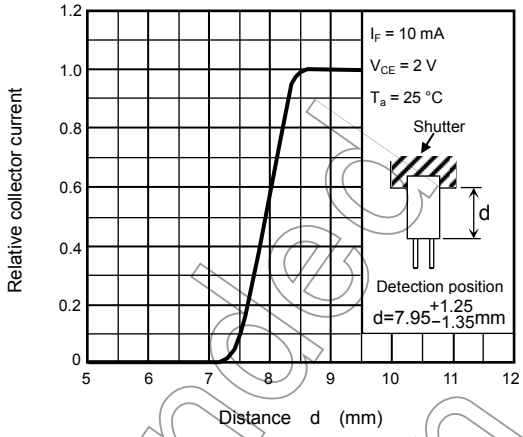
Detection position Characteristics(1) (typ.)

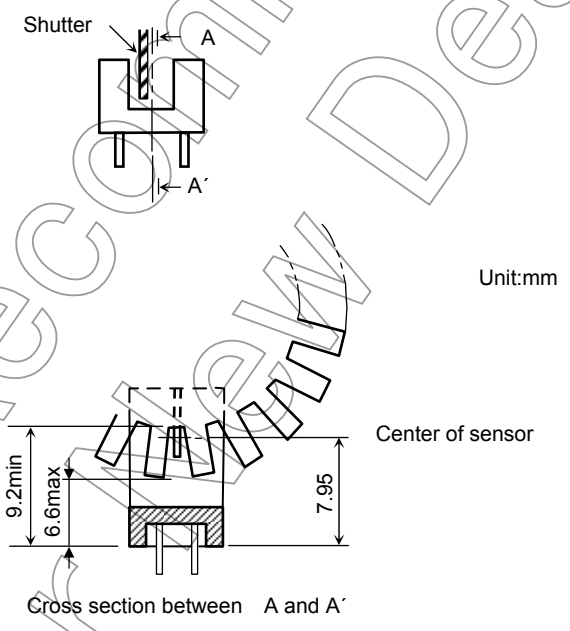


Detection position Characteristics(2) (typ.)



Relative Positioning Of Shutter And Device

For normal operation position the shutter and the device as shown in the figure below. By considering the device's detection direction characteristic and switching time, determine the shutter slit width and pitch.



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